

MC7323-VB Datasheet

P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^c	Q _g (Typ.)			
- 20	0.080 at V _{GS} = - 4.5 V	- 3.1	4.3 nC			
	0.100 at V _{GS} = - 2.5 V	- 2.3	4.5110			

FEATURES

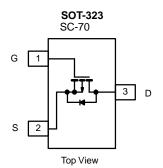
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

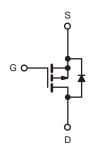


HALOGEN FREE

APPLICATIONS

- Load Switch
- DC/DC Converters





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless oth Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	- 20	Oilit
Gate-Source Voltage		V _{GS}	± 12	V
	T _C = 25 °C		- 3.1	
Ocationary Preis Oceanal (T., 450.00)	T _C = 70 °C	1 . —	- 2.1	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	- 1.4 ^{a, b}	
	T _A = 70 °C		- 1.1 ^{a, b}	А
Pulsed Drain Current		I _{DM}	- 6	
Ocaliana Ocana Baria Birda Ocana	T _C = 25 °C		- 0.4	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 0.3	
	T _C = 25 °C		0.5	
Maximum Dawar Dissination	T _C = 70 °C	P _D	0.3	w
Maximum Power Dissipation	T _A = 25 °C] 'D	0.4 ^{a, b}	VV
	T _A = 70 °C		0.3 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 50 to 150	°C
Soldering Recommendations (Peak Temperature)			260	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Based on T_C = 25 °C.



THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, b}	t ≤ 10 s	R _{thJA}	250	300	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	225	270	5/ * *	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Maximum under steady state conditions is 360 °C/W.

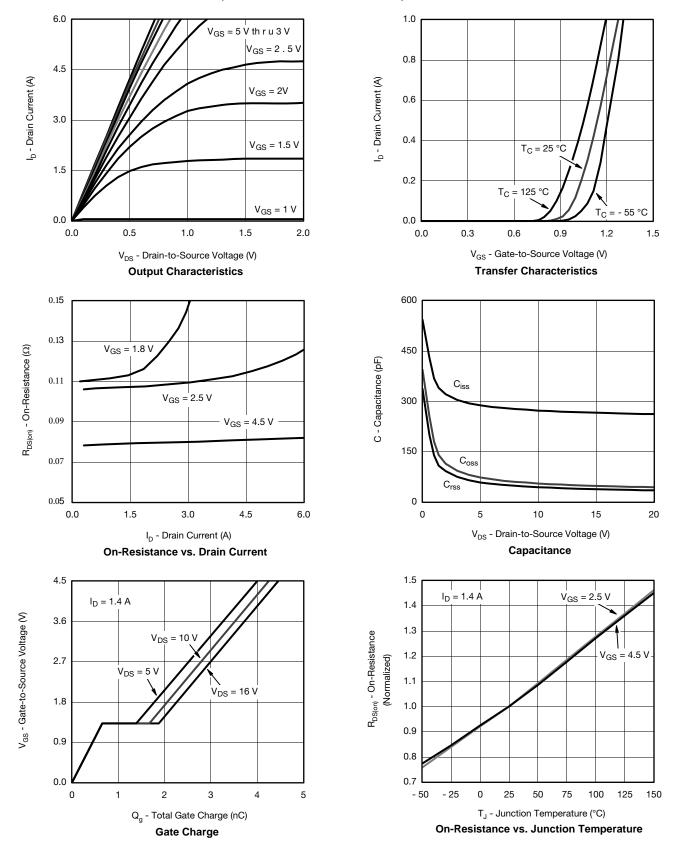
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$	- 20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 - 250		- 14		m\//º/
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		2.4		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 0.45		- 1.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
Zara Cata Valtaga Praia Current	1	V _{DS} = - 20 V, V _{GS} = 0 V			- 1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 2			Α
	, ,	V _{GS} = - 4.5 V, I _D = - 1.4 A		0.080		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 1.2 A		0.100		
	,	V _{GS} = - 1.8 V, I _D = - 0.3 A		0.140		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 5 V, I _D = - 1.4 A		5		S
Dynamic ^b						
Input Capacitance	C _{iss}			272		pF
Output Capacitance	C _{oss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		55		
Reverse Transfer Capacitance	C _{rss}			44		
		$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.4 \text{ A}$		4.3	6.5	
Total Gate Charge	Q _g -	50 5		2.7	4.1	nC
Gate-Source Charge		$V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -1.4 \text{ A}$		0.7		
Gate-Drain Charge	Q_{gd}			1.0		
Gate Resistance	R _q	f = 1 MHz	1.4	7	14	Ω
Turn-On Delay Time	t _{d(on)}			12	20	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_1 = 9.1 \Omega$		20	30	ns
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1.1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		23	35	
Fall Time	t _f	_		9	18	
Turn-On Delay Time	t _{d(on)}			5	10	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_1 = 9.1 \Omega$		10	20	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1.1 \text{ A, } V_{GEN} = -8 \text{ V, } R_g = 1 \Omega$		18	27	1
Fall Time	t _f	Ĭ		7	14	1
Drain-Source Body Diode Characterist						
Continuous Source-Drain Diode Current I_S $T_C = 25$ °C Pulse Diode Forward Current I_{SM}		T _C = 25 °C			- 2.4	
		Ü			- 6	A
Body Diode Voltage	V _{SD}	I _F = - 0.7 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	·		18	27	ns
Body Diode Reverse Recovery Charge	Q _{rr}			7	14	nC
Reverse Recovery Fall Time	t _a	$I_F = -0.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/µs}, T_J = 25 ^{\circ}\text{C}$		7		\top
Reverse Recovery Rise Time	t _b			11		ns

Notes:

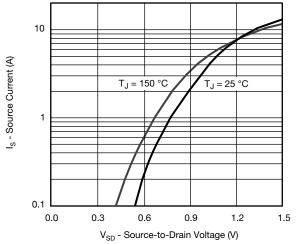
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

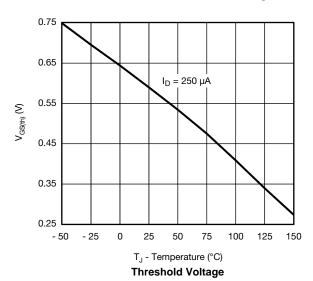


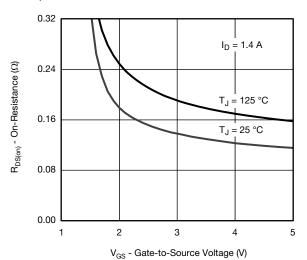




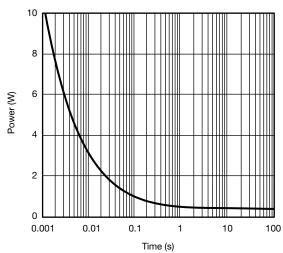


Source-Drain Diode Forward Voltage

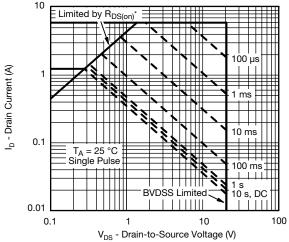




On-Resistance vs. Gate-to-Source Voltage



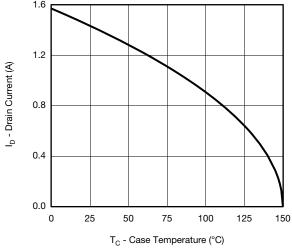
Single Pulse Power, Junction-to-Ambient



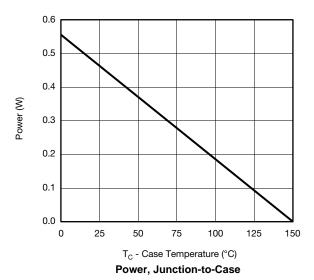
 * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

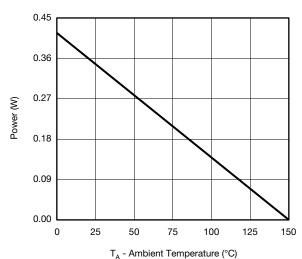
Safe Operating Area, Junction-to-Ambient





Current Derating*

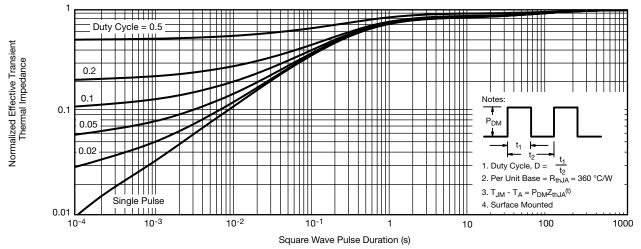




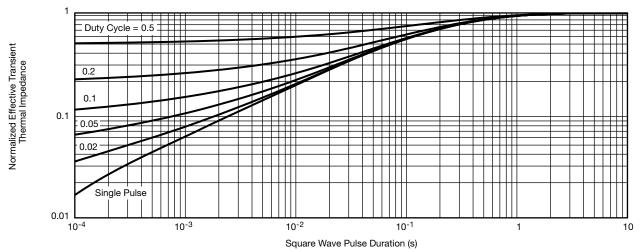
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





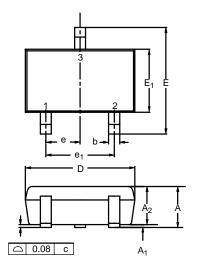
Normalized Thermal Transient Impedance, Junction-to-Ambient

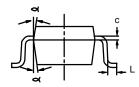


Normalized Thermal Transient Impedance, Junction-to-Foot



SC-70: 3-LEADS

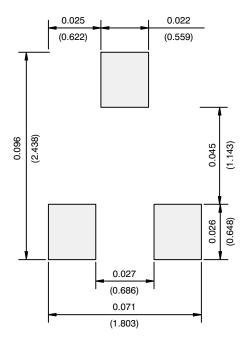




	MIL	LIMET	ERS	INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.90	_	1.10	0.035	_	0.043	
A_1	-	-	0.10	-	_	0.004	
A ₂	0.80	_	1.00	0.031	_	0.039	
b	0.25	-	0.40	0.010	_	0.016	
С	0.10	_	0.25	0.004	-	0.010	
D	1.80	2.00	2.20	0.071	0.079	0.087	
Ε	1.80	2.10	2.40	0.071	0.083	0.094	
E ₁	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65BSC			0.026BSC			
e ₁	1.20	1.30	1.40	0.047	0.051	0.055	
L	0.10	0.20	0.30	0.004	0.008	0.012	
٦	7°Nom			7°Nom			



RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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